ABSTRACT OF THE DISCLOSURE

A bonding apparatus has a bonding tool for holding a chip on a mount surface, an elevating mechanism for elevating the bonding tool, and a chip recognition camera for taking a picture of the chip from its lower side. A detecting device is provided for detecting contact between the chip and the bonding tool. A controlling device is provided for displacing the bonding tool from the position where the detection means has detected contact between the chip and the bonding tool by an amount, in the height direction, equal to a difference between the mount surface and a focal position of the chip recognition camera, so as to place the bonding tool above the chip recognition camera.

This Sheet Has Been Replaced